



# PDTD1xxxU series

500 mA, 50 V NPN resistor-equipped transistors

Rev. 1 — 13 May 2014

Product data sheet

## 1. Product profile

### 1.1 General description

NPN Resistor-Equipped Transistor (RET) family in a very small SOT323 (SC-70) Surface-Mounted Device (SMD) plastic package.

Table 1. Product overview

Type number	Package			PNP complement	Package configuration
	NXP	JEITA	JEDEC		
PDTD113EU	SOT323	SC-70	-	PDTB113EU	very small
PDTD113ZU				PDTB113ZU	
PDTD123EU				PDTB123EU	
PDTD123YU				PDTB123YU	
PDTD143EU				PDTB143EU	
PDTD143XU				PDTB143XU	
PDTD114EU				PDTB114EU	

### 1.2 Features

- 500 mA output current capability
- Built-in bias resistors
- Simplifies circuit design
- Reduces component count
- $\pm 10\%$  resistor ratio tolerance
- AEC-Q101 qualified
- High temperature applications up to 175 °C

### 1.3 Applications

- IC inputs control
- Cost-saving alternative to BC807 or BC817 series transistors in digital applications
- Switching loads



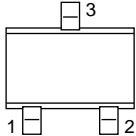
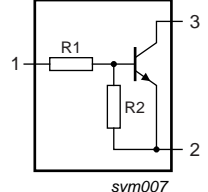
## 1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CE0}$	collector-emitter voltage	open base	-	-	50	V
$I_O$	output current		-	-	500	mA
R1	bias resistor 1 (input)					
	PDTD113EU			1		k $\Omega$
	PDTD113ZU			1		k $\Omega$
	PDTD123EU			2.2		k $\Omega$
	PDTD123YU			2.2		k $\Omega$
	PDTD143EU			4.7		k $\Omega$
	PDTD143XU			4.7		k $\Omega$
	PDTD114EU			10		k $\Omega$
R2	bias resistor 2 (base-emitter)					
	PDTD113EU			1		k $\Omega$
	PDTD113ZU			10		k $\Omega$
	PDTD123EU			2.2		k $\Omega$
	PDTD123YU			10		k $\Omega$
	PDTD143EU			4.7		k $\Omega$
	PDTD143XU			10		k $\Omega$
	PDTD114EU			10		k $\Omega$

## 2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	input (base)		 <p style="text-align: center;"><i>sym007</i></p>
2	GND (emitter)		
3	output (collector)		

## 3. Ordering information

Table 4. Ordering information

Type number	Package		
	Name	Description	Version
PDTD1xxxU series	SC-70	plastic surface-mounted package; 3 leads	SOT323

## 4. Marking

Table 5. Marking codes

Type number	Marking code <sup>[1]</sup>
PDTD113EU	ZP*
PDTD113ZU	ZQ*
PDTD123EU	ZR*
PDTD123YU	ZS*
PDTD143EU	ZT*
PDTD143XU	ZU*
PDTD114EU	ZV*

[1] \* = placeholder for manufacturing site code

## 5. Limiting values

Table 6. Limiting values

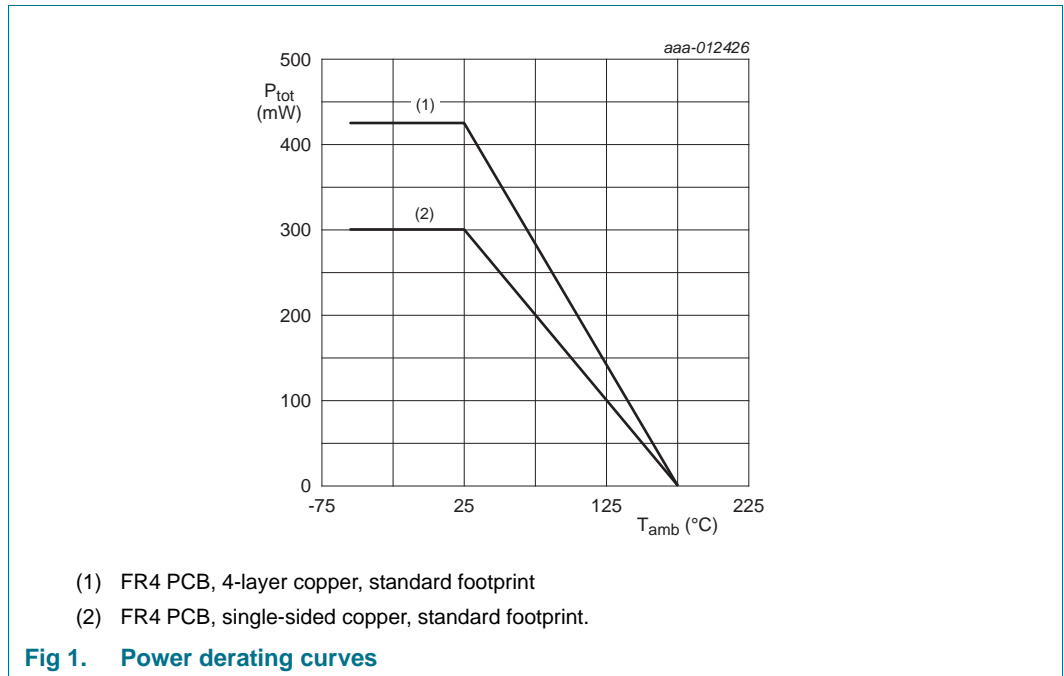
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter	-	50	V
$V_{CEO}$	collector-emitter voltage	open base	-	50	V
$V_{EBO}$	emitter-base voltage	open collector			
	PDTD113EU		-	10	V
	PDTD113ZU		-	5	V
	PDTD123EU		-	10	V
	PDTD123YU		-	5	V
	PDTD143EU		-	10	V
	PDTD143XU		-	7	V
	PDTD114EU		-	10	V
$V_I$	input voltage				
	PDTD113EU		-10	+10	V
	PDTD113ZU		-5	+10	V
	PDTD123EU		-10	+12	V
	PDTD123YU		-5	+12	V
	PDTD143EU		-10	+30	V
	PDTD143XU		-7	+30	V
	PDTD114EU		-10	+50	V
$I_O$	output current		-	500	mA

**Table 6. Limiting values ...continued**  
 In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[1]	300	mW
			[2]	425	mW
T <sub>j</sub>	junction temperature		-	175	°C
T <sub>amb</sub>	ambient temperature		-55	+175	°C
T <sub>stg</sub>	storage temperature		-55	+175	°C

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.

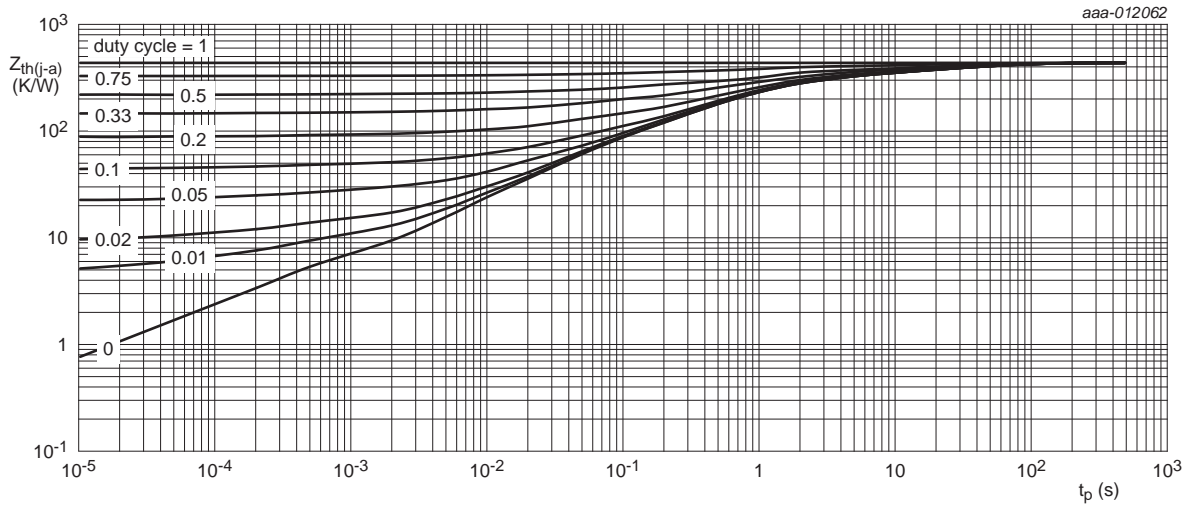


## 6. Thermal characteristics

**Table 7. Thermal characteristics**

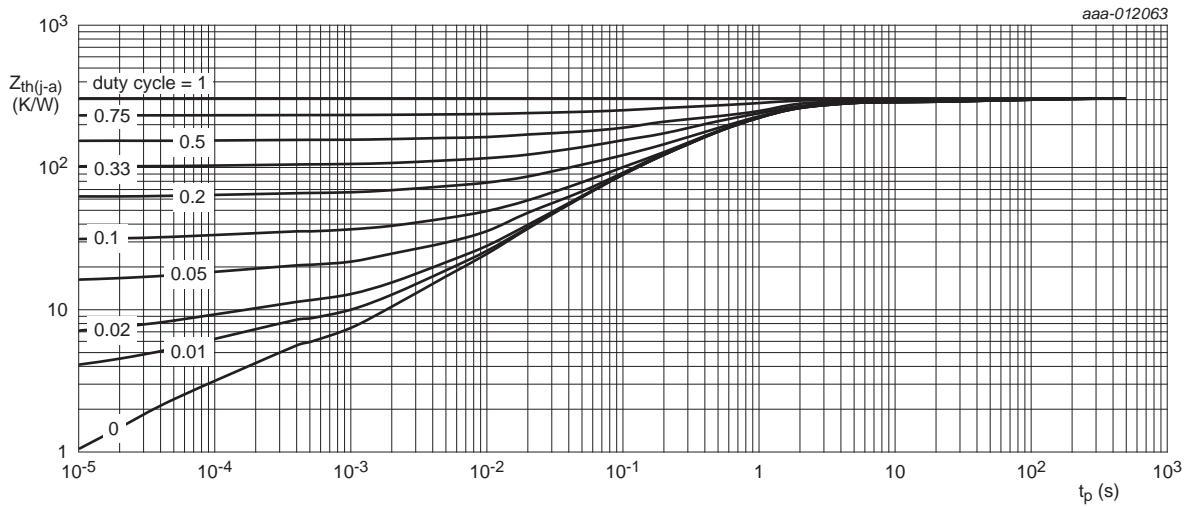
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air	[1]	-	500	K/W
			[2]	-	353	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.



FR4 PCB, single-sided copper, tin-plated and standard footprint

**Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT323/SC-70; typical values**



FR4 PCB, 4-layer copper, tin-plated and standard footprint.

**Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT323/SC-70; typical values**

## 7. Characteristics

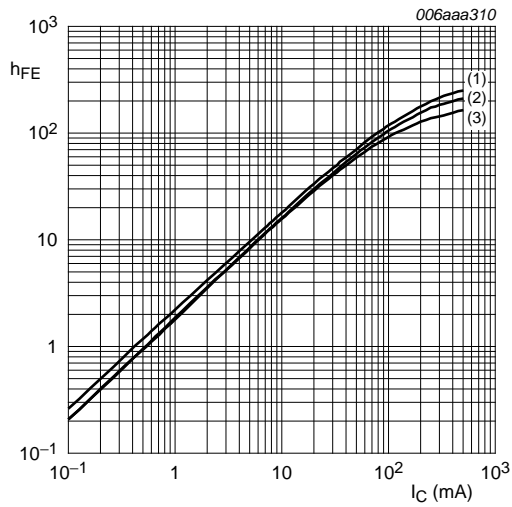
**Table 8. Characteristics**
 $T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = 40 V; I <sub>E</sub> = 0 A	-	-	100	nA
		V <sub>CB</sub> = 50 V; I <sub>E</sub> = 0 A	-	-	100	nA
I <sub>CEO</sub>	collector-emitter cut-off current	V <sub>CE</sub> = 50 V; I <sub>B</sub> = 0 A	-	-	0.5	μA
I <sub>EBO</sub>	emitter-base cut-off current	V <sub>EB</sub> = 5 V; I <sub>C</sub> = 0 A				
	PDTD113EU		-	-	4.0	mA
	PDTD113ZU		-	-	0.8	mA
	PDTD123EU		-	-	2.0	mA
	PDTD123YU		-	-	0.65	mA
	PDTD143EU		-	-	0.9	mA
	PDTD143XU		-	-	0.6	mA
	PDTD114EU		-	-	0.4	mA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 5 V; I <sub>C</sub> = 50 mA				
	PDTD113EU		33	-	-	
	PDTD113ZU		70	-	-	
	PDTD123EU		40	-	-	
	PDTD123YU		70	-	-	
	PDTD143EU		60	-	-	
	PDTD143XU		70	-	-	
	PDTD114EU		70	-	-	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = 50 mA; I <sub>B</sub> = 2.5 mA	-	-	100	mV
V <sub>I(off)</sub>	off-state input voltage	V <sub>CE</sub> = 5 V; I <sub>C</sub> = 100 μA				
	PDTD113EU		0.6	1.1	1.5	V
	PDTD113ZU		0.3	0.6	1.0	V
	PDTD123EU		0.6	1.1	1.8	V
	PDTD123YU		0.4	0.6	1.0	V
	PDTD143EU		0.6	0.9	1.5	V
	PDTD143XU		0.5	0.75	1.1	V
	PDTD114EU		0.6	1.0	1.5	V
V <sub>I(on)</sub>	on-state input voltage	V <sub>CE</sub> = 0.3 V; I <sub>C</sub> = 20 mA				
	PDTD113EU		1.0	1.4	1.8	V
	PDTD113ZU		0.4	0.8	1.4	V
	PDTD123EU		1.0	1.5	2.0	V
	PDTD123YU		0.5	1.0	1.4	V
	PDTD143EU		1.0	1.6	2.2	V
	PDTD143XU		1.0	1.25	2.0	V
	PDTD114EU		1.0	1.9	3.0	V

**Table 8. Characteristics ...continued**  
 $T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

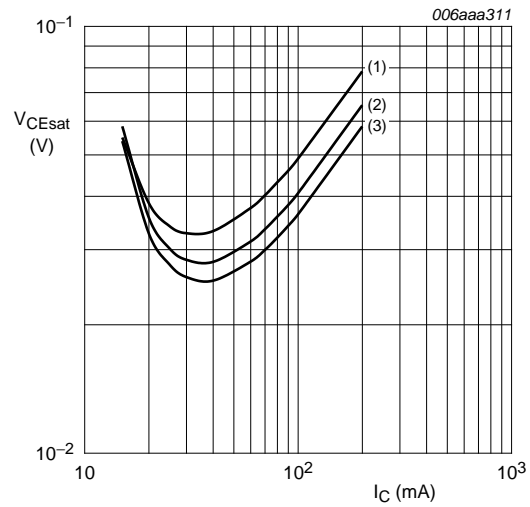
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R1	bias resistor 1 (input)					
	PDTD113EU		0.7	1.0	1.3	k $\Omega$
	PDTD113ZU		0.7	1.0	1.3	k $\Omega$
	PDTD123EU		1.54	2.2	2.86	k $\Omega$
	PDTD123YU		1.54	2.2	2.86	k $\Omega$
	PDTD143EU		3.3	4.7	6.1	k $\Omega$
	PDTD143XU		3.3	4.7	6.1	k $\Omega$
	PDTD114EU		7.0	10	13	k $\Omega$
R2/R1	bias resistor ratio					
	PDTD113EU		0.9	1.0	1.1	
	PDTD113ZU		9.0	10	11	
	PDTD123EU		0.9	1.0	1.1	
	PDTD123YU		4.1	4.55	5.0	
	PDTD143EU		0.9	1	1.1	
	PDTD143XU		1.91	2.13	2.34	
	PDTD114EU		0.9	1.0	1.1	
C <sub>c</sub>	collector capacitance	V <sub>CB</sub> = 10 V; I <sub>E</sub> = i <sub>e</sub> = 0 A; f = 1 MHz	-	7	-	pF
f <sub>T</sub>	transition frequency	V <sub>CE</sub> = 5 V; I <sub>C</sub> = 50 mA; f = 100 MHz	[1]	225	-	MHz

[1] Characteristics of built-in transistor.



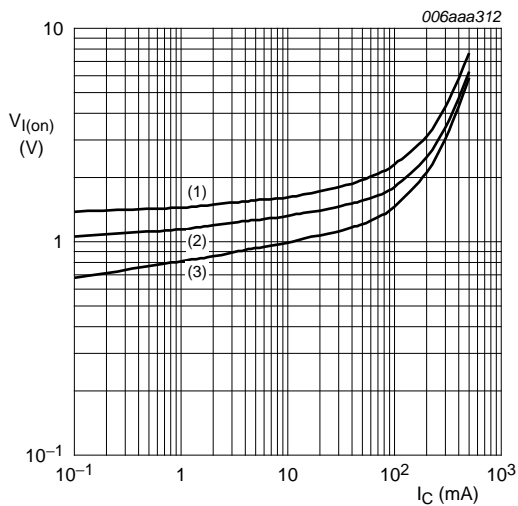
$V_{CE} = 5 \text{ V}$   
 (1)  $T_{amb} = 100 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = -40 \text{ }^\circ\text{C}$

**Fig 4. PDTD113EU: DC current gain as a function of collector current; typical values**



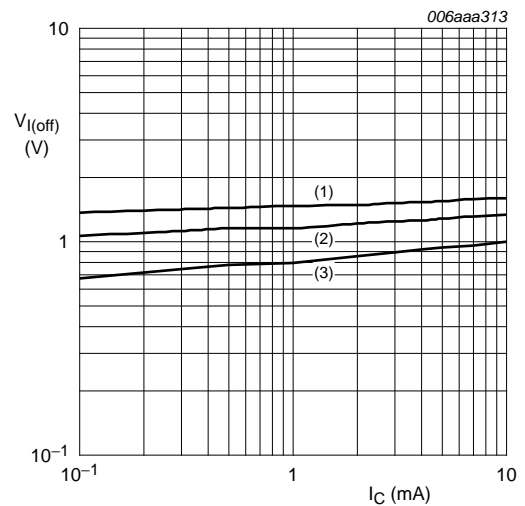
$I_C/I_B = 20$   
 (1)  $T_{amb} = 100 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = -40 \text{ }^\circ\text{C}$

**Fig 5. PDTD113EU: Collector-emitter saturation voltage as a function of collector current; typical values**



$V_{CE} = 0.3 \text{ V}$   
 (1)  $T_{amb} = -40 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = 100 \text{ }^\circ\text{C}$

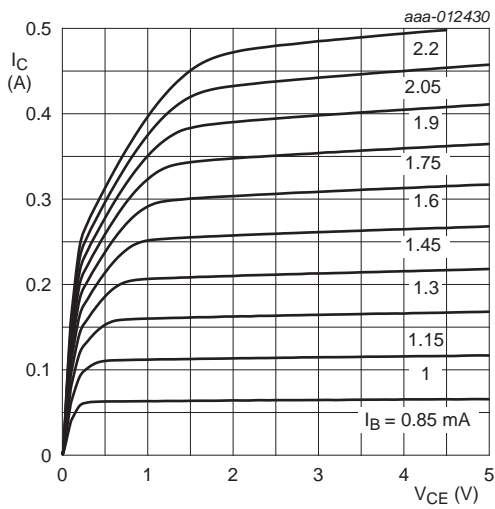
**Fig 6. PDTD113EU: On-state input voltage as a function of collector current; typical values**



$V_{CE} = 5 \text{ V}$   
 (1)  $T_{amb} = -40 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = 100 \text{ }^\circ\text{C}$

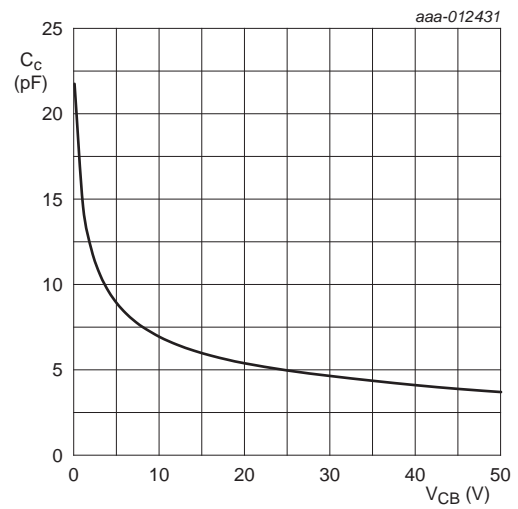
**Fig 7. PDTD113EU: Off-state input voltage as a function of collector current; typical values**





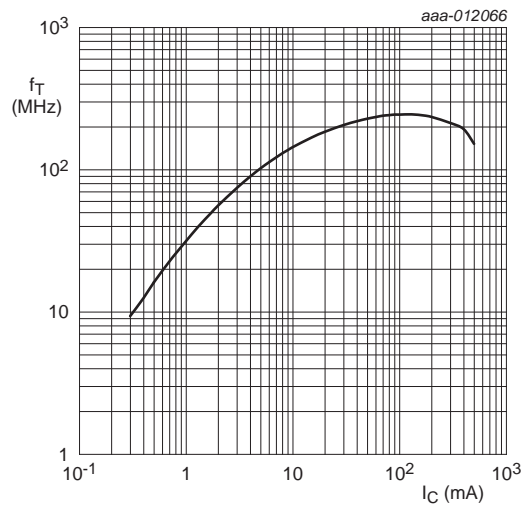
$T_{amb} = 25\text{ }^\circ\text{C}$

**Fig 8. PDTD113EU: Collector current as a function of collector-emitter voltage; typical values**



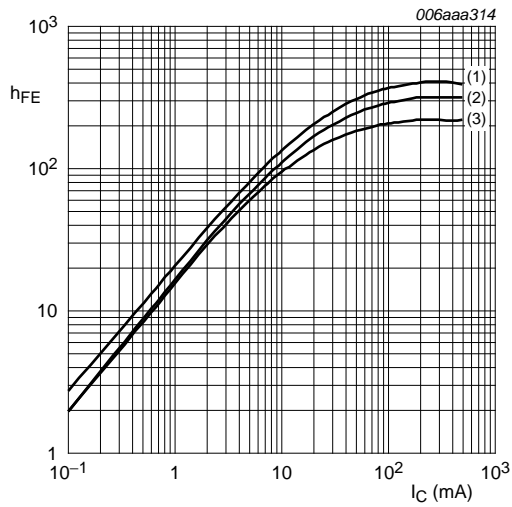
$f = 1\text{ MHz}; T_{amb} = 25\text{ }^\circ\text{C}$

**Fig 9. PDTD113EU: Collector capacitance as a function of collector-base voltage; typical values**



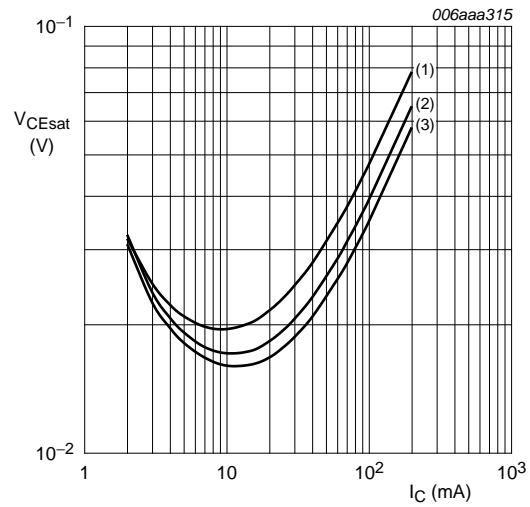
$V_{CE} = 5\text{ V}; T_{amb} = 25\text{ }^\circ\text{C}$

**Fig 10. PDTD113EU: Transition frequency as a function of collector current; typical values of built-in transistor**



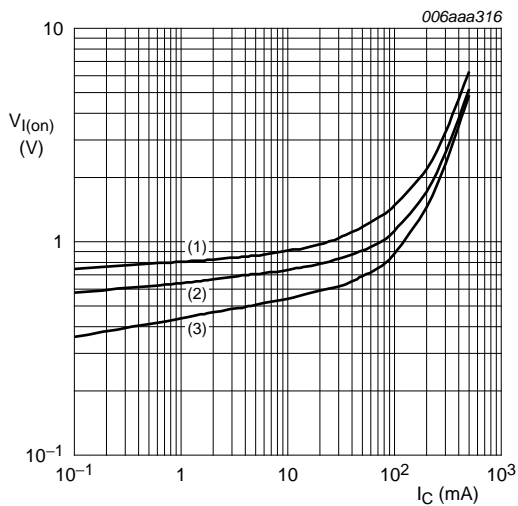
$V_{CE} = 5 \text{ V}$   
 (1)  $T_{amb} = 100 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = -40 \text{ }^\circ\text{C}$

**Fig 11. PDTD113ZU: DC current gain as a function of collector current; typical values**



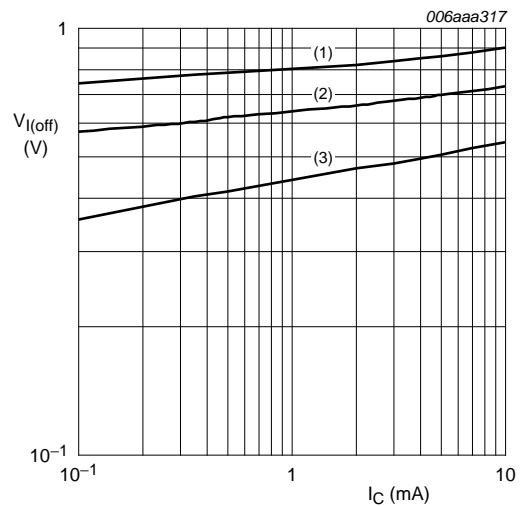
$I_C/I_B = 20$   
 (1)  $T_{amb} = 100 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = -40 \text{ }^\circ\text{C}$

**Fig 12. PDTD113ZU: Collector-emitter saturation voltage as a function of collector current; typical values**



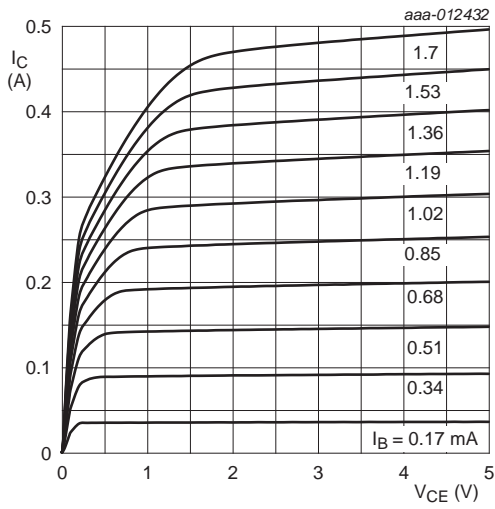
$V_{CE} = 0.3 \text{ V}$   
 (1)  $T_{amb} = -40 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = 100 \text{ }^\circ\text{C}$

**Fig 13. PDTD113ZU: On-state input voltage as a function of collector current; typical values**



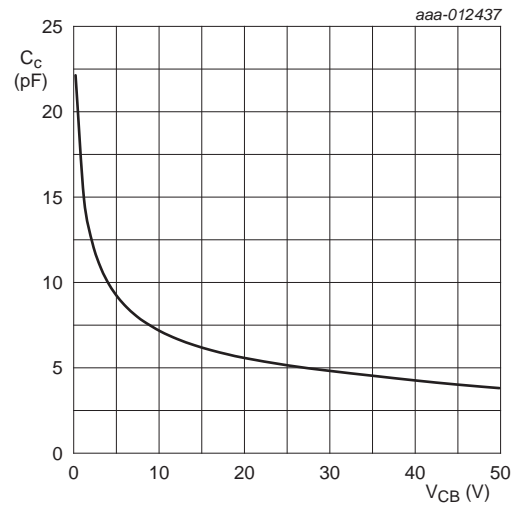
$V_{CE} = 5 \text{ V}$   
 (1)  $T_{amb} = -40 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = 100 \text{ }^\circ\text{C}$

**Fig 14. PDTD113ZU: Off-state input voltage as a function of collector current; typical values**



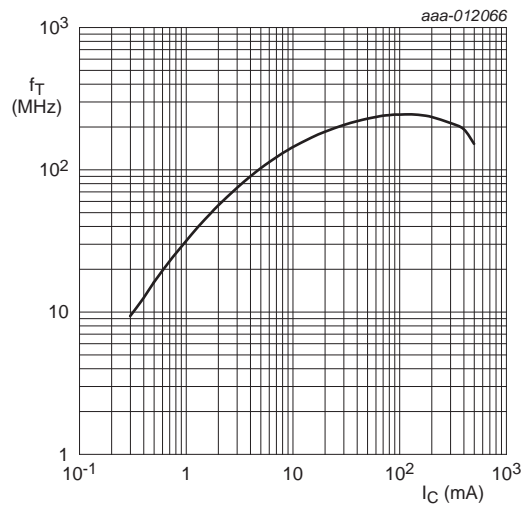
$T_{amb} = 25$  °C

**Fig 15. PDTD113ZU: Collector current as a function of collector-emitter voltage; typical values**



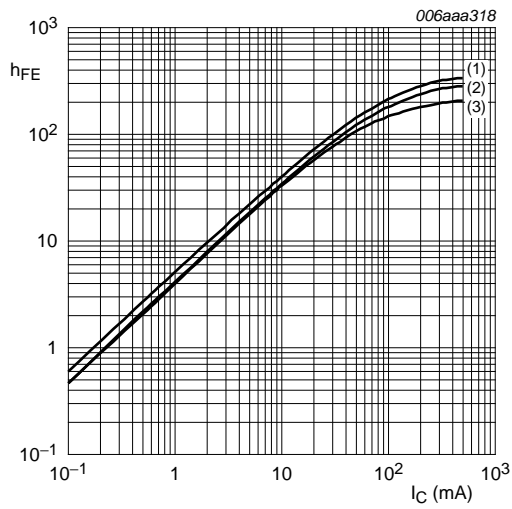
$f = 1$  MHz;  $T_{amb} = 25$  °C

**Fig 16. PDTD113ZU: Collector capacitance as a function of collector-base voltage; typical values**



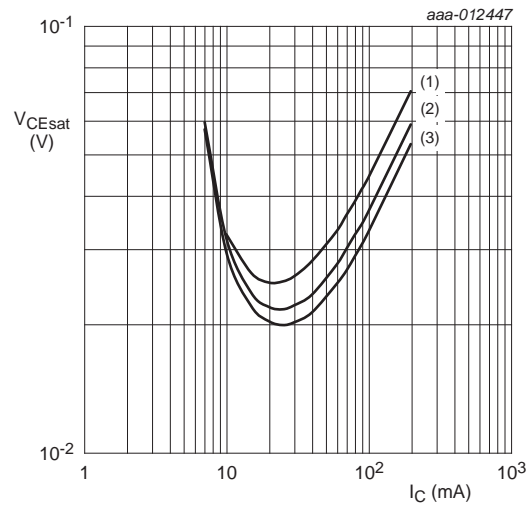
$V_{CE} = 5$  V;  $T_{amb} = 25$  °C

**Fig 17. PDTD113ZU: Transition frequency as a function of collector current; typical values of built-in transistor**



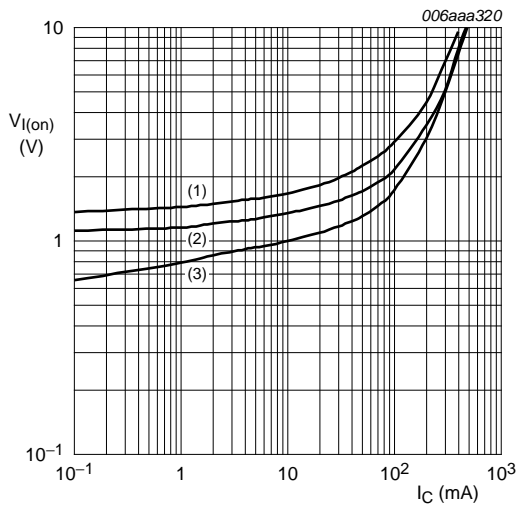
$V_{CE} = 5 \text{ V}$   
 (1)  $T_{amb} = 100 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = -40 \text{ }^\circ\text{C}$

**Fig 18. PDTD123EU: DC current gain as a function of collector current; typical values**



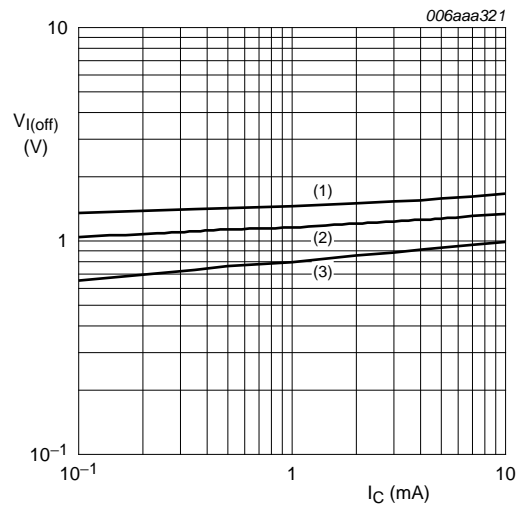
$I_C/I_B = 20$   
 (1)  $T_{amb} = 100 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = -40 \text{ }^\circ\text{C}$

**Fig 19. PDTD123EU: Collector-emitter saturation voltage as a function of collector current; typical values**



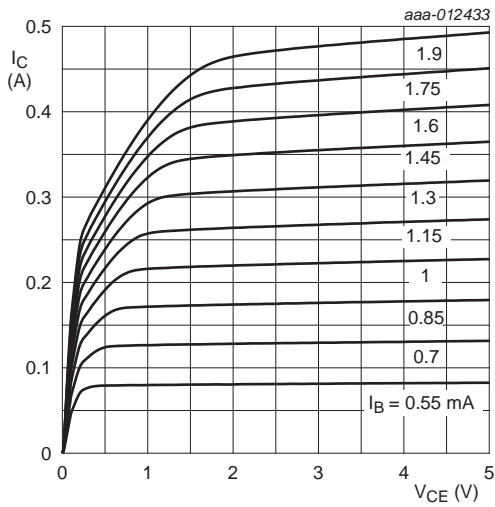
$V_{CE} = 0.3 \text{ V}$   
 (1)  $T_{amb} = -40 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = 100 \text{ }^\circ\text{C}$

**Fig 20. PDTD123EU: On-state input voltage as a function of collector current; typical values**



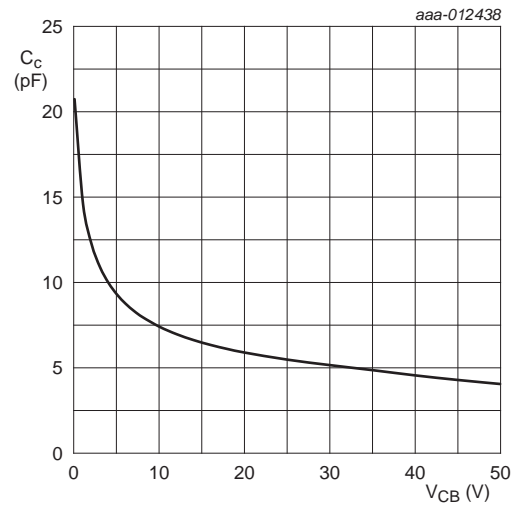
$V_{CE} = 5 \text{ V}$   
 (1)  $T_{amb} = -40 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = 100 \text{ }^\circ\text{C}$

**Fig 21. PDTD123EU: Off-state input voltage as a function of collector current; typical values**



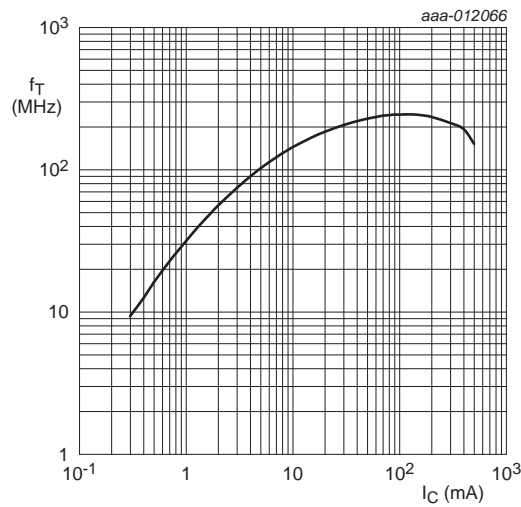
$T_{amb} = 25\text{ }^\circ\text{C}$

**Fig 22. PDTD123EU: Collector current as a function of collector-emitter voltage; typical values**



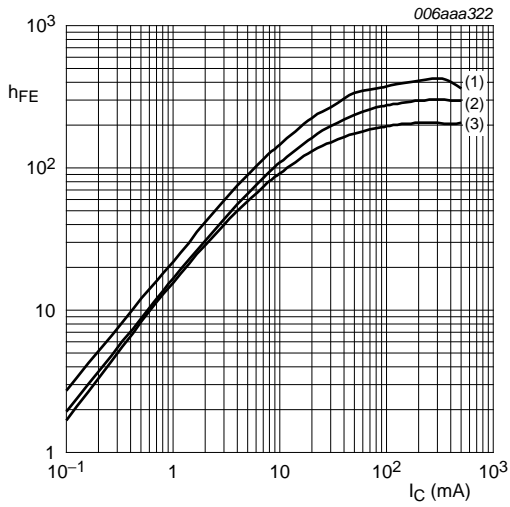
$f = 1\text{ MHz}; T_{amb} = 25\text{ }^\circ\text{C}$

**Fig 23. PDTD123EU: Collector capacitance as a function of collector-base voltage; typical values**



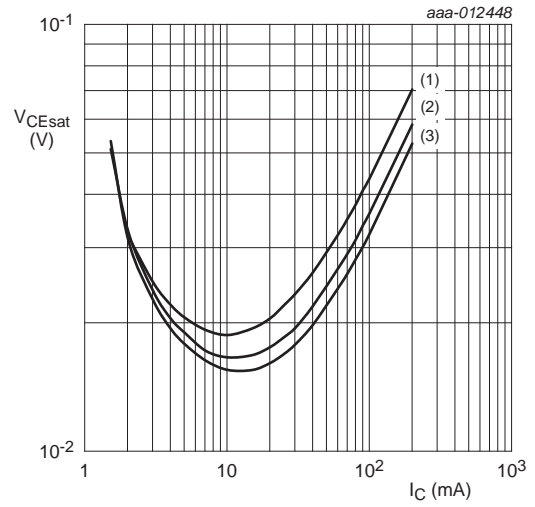
$V_{CE} = 5\text{ V}; T_{amb} = 25\text{ }^\circ\text{C}$

**Fig 24. PDTD123EU: Transition frequency as a function of collector current; typical values of built-in transistor**



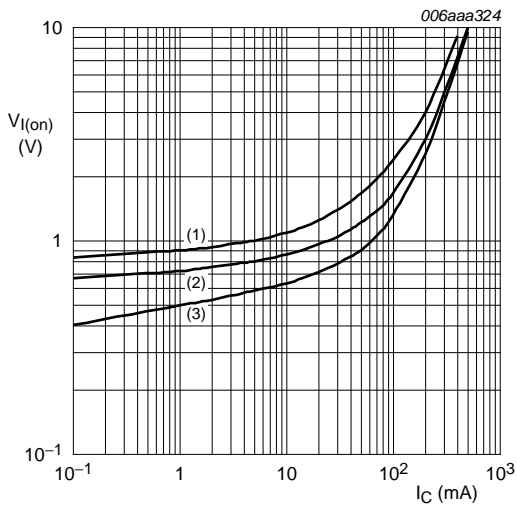
$V_{CE} = 5\text{ V}$   
 (1)  $T_{amb} = 100\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -40\text{ °C}$

**Fig 25. PDTD123YU: DC current gain as a function of collector current; typical values**



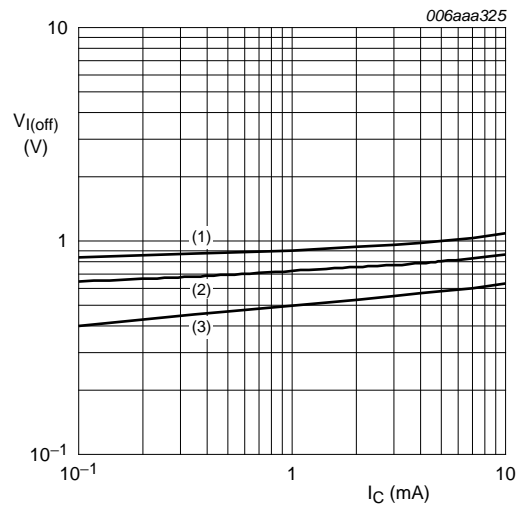
$I_C/I_B = 20$   
 (1)  $T_{amb} = 100\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -40\text{ °C}$

**Fig 26. PDTD123YU: Collector-emitter saturation voltage as a function of collector current; typical values**



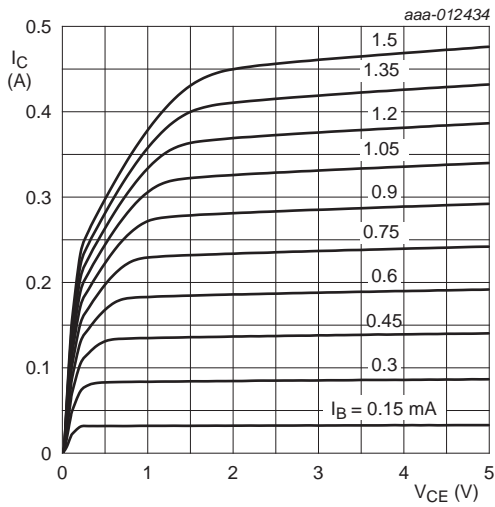
$V_{CE} = 0.3\text{ V}$   
 (1)  $T_{amb} = -40\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = 100\text{ °C}$

**Fig 27. PDTD123YU: On-state input voltage as a function of collector current; typical values**

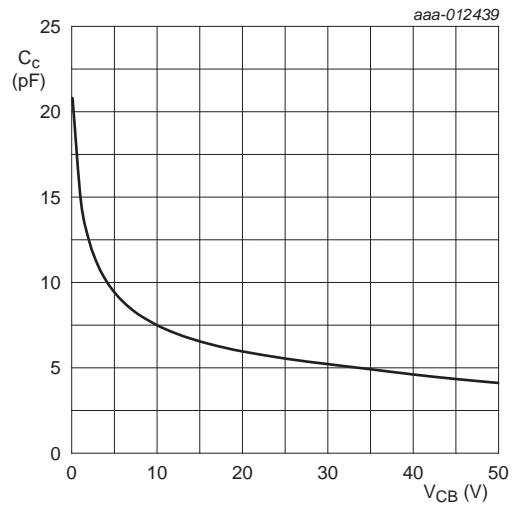


$V_{CE} = 5\text{ V}$   
 (1)  $T_{amb} = -40\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = 100\text{ °C}$

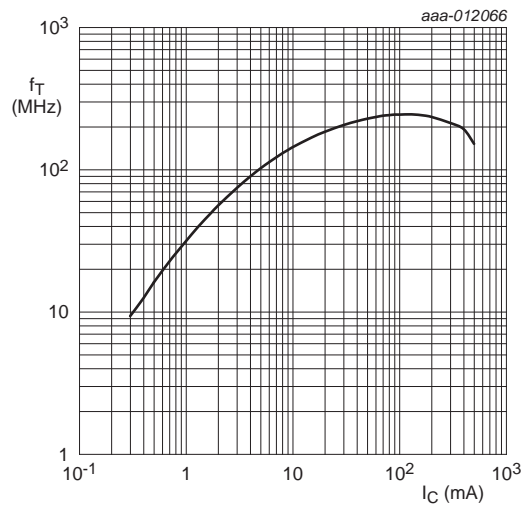
**Fig 28. PDTD123YU: Off-state input voltage as a function of collector current; typical values**



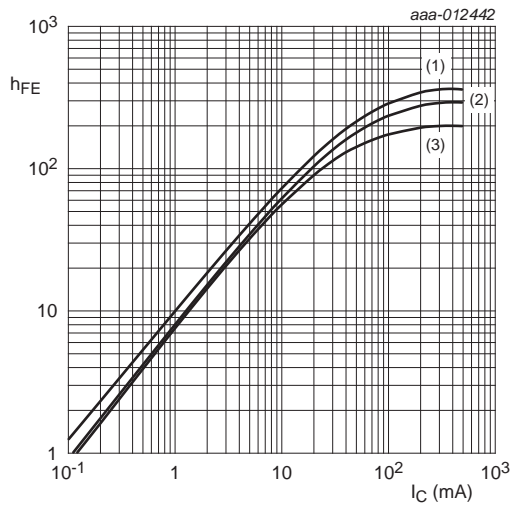
**Fig 29. PDTD123YU: Collector current as a function of collector-emitter voltage; typical values**



**Fig 30. PDTD123YU: Collector capacitance as a function of collector-base voltage; typical values**

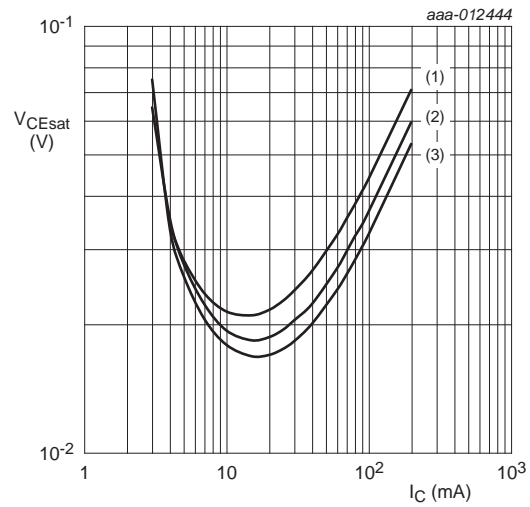


**Fig 31. PDTD123YU: Transition frequency as a function of collector current; typical values of built-in transistor**



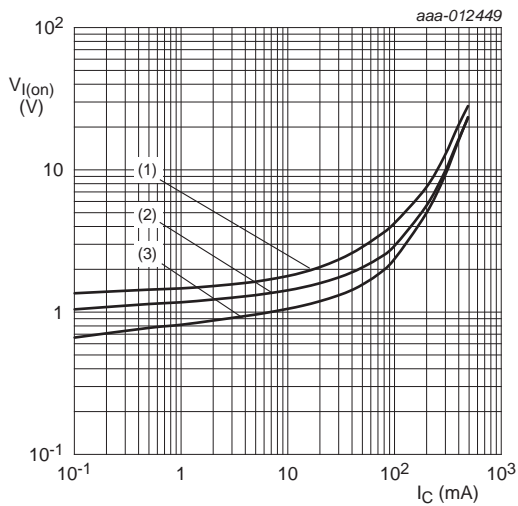
$V_{CE} = 5\text{ V}$   
 (1)  $T_{amb} = 100\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -40\text{ °C}$

**Fig 32. PDTD143EU: DC current gain as a function of collector current; typical values**



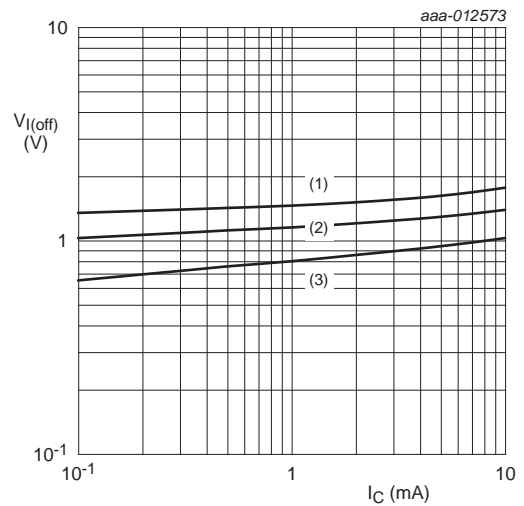
$I_C/I_B = 20$   
 (1)  $T_{amb} = 100\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -40\text{ °C}$

**Fig 33. PDTD143EU: Collector-emitter saturation voltage as a function of collector current; typical values**



$V_{CE} = 0.3\text{ V}$   
 (1)  $T_{amb} = -40\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = 100\text{ °C}$

**Fig 34. PDTD143EU: On-state input voltage as a function of collector current; typical values**



$V_{CE} = 5\text{ V}$   
 (1)  $T_{amb} = -40\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = 100\text{ °C}$

**Fig 35. PDTD143EU: Off-state input voltage as a function of collector current; typical values**



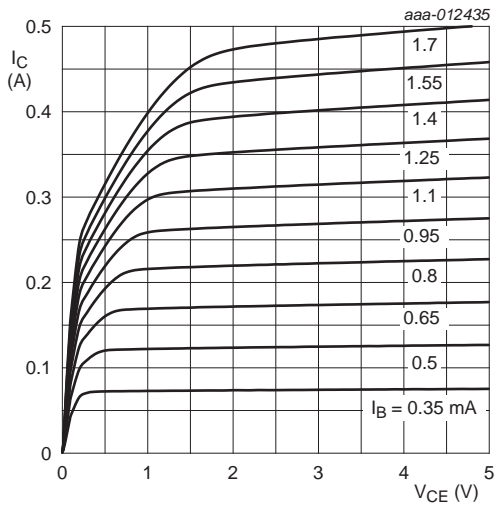


Fig 36. PDTD143EU: Collector current as a function of collector-emitter voltage; typical values

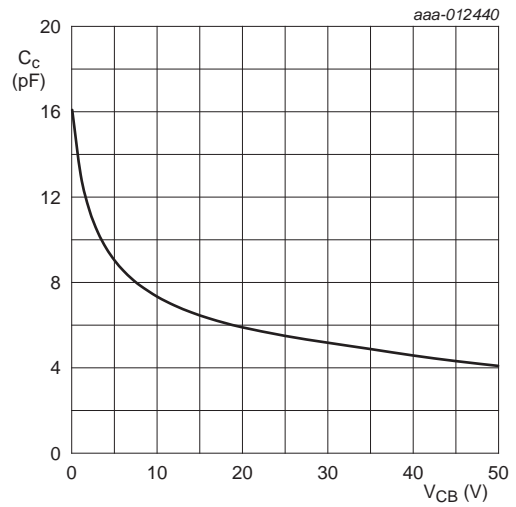
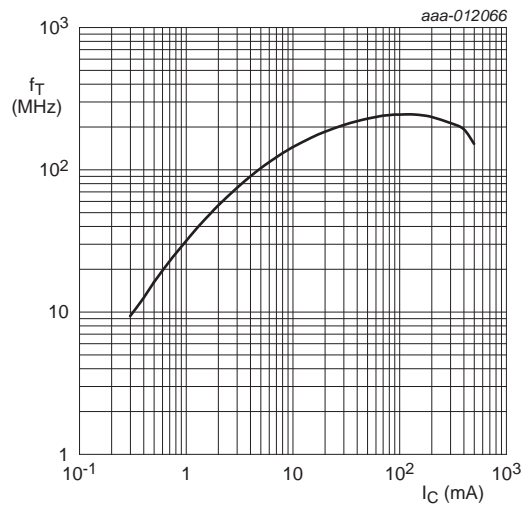
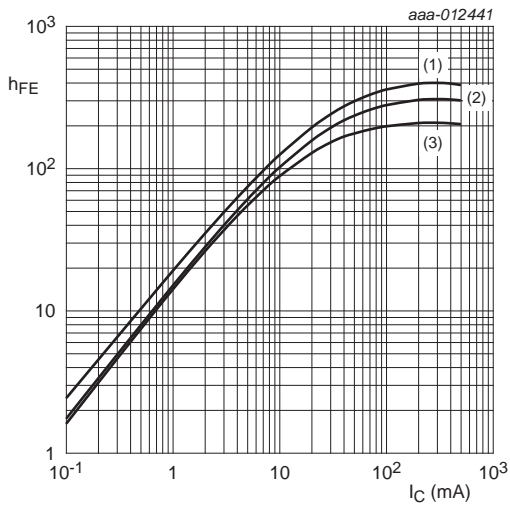


Fig 37. PDTD143EU: Collector capacitance as a function of collector-base voltage; typical values



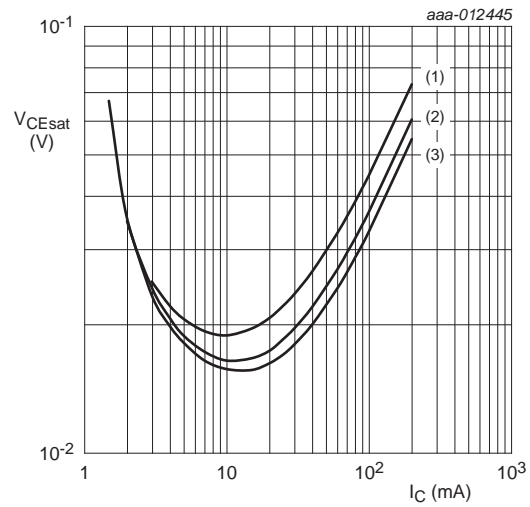
$V_{CE} = 5\text{ V}$ ;  $T_{amb} = 25\text{ }^\circ\text{C}$

Fig 38. PDTD143EU: Transition frequency as a function of collector current; typical values of built-in transistor



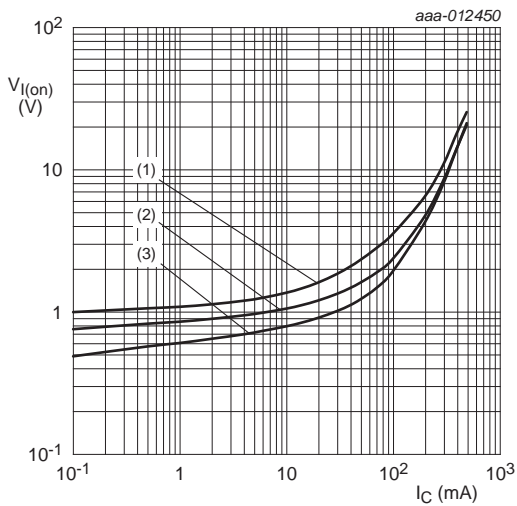
$V_{CE} = 5\text{ V}$   
 (1)  $T_{amb} = 100\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -40\text{ °C}$

**Fig 39. PDTD143XU: DC current gain as a function of collector current; typical values**



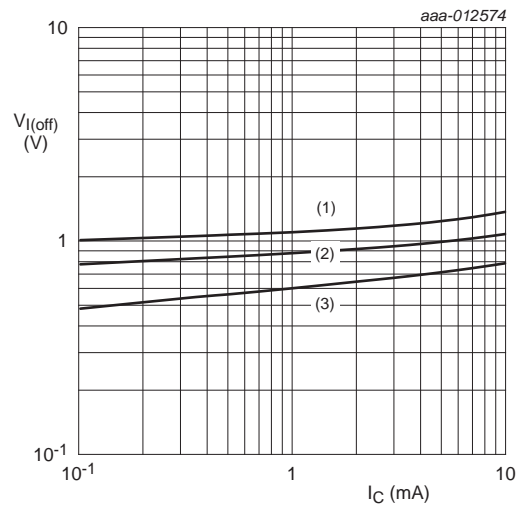
$I_C/I_B = 20$   
 (1)  $T_{amb} = 100\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -40\text{ °C}$

**Fig 40. PDTD143XU: Collector-emitter saturation voltage as a function of collector current; typical values**



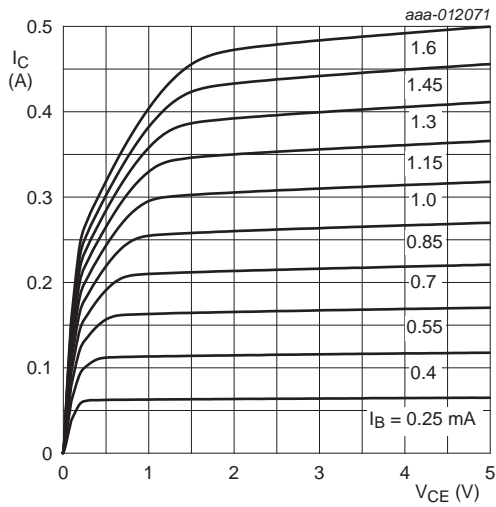
$V_{CE} = 0.3\text{ V}$   
 (1)  $T_{amb} = -40\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = 100\text{ °C}$

**Fig 41. PDTD143XU: On-state input voltage as a function of collector current; typical values**



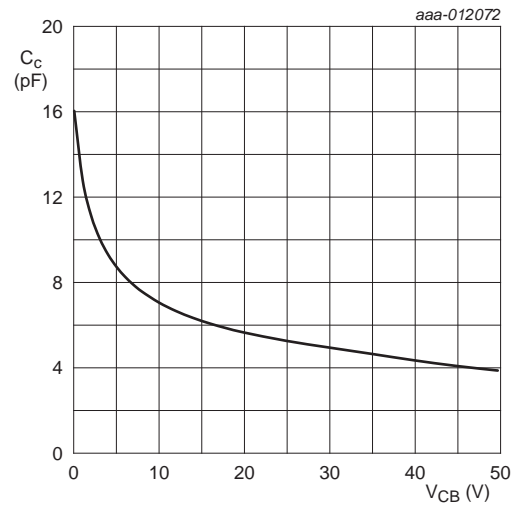
$V_{CE} = 5\text{ V}$   
 (1)  $T_{amb} = -40\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = 100\text{ °C}$

**Fig 42. PDTD143XU: Off-state input voltage as a function of collector current; typical values**



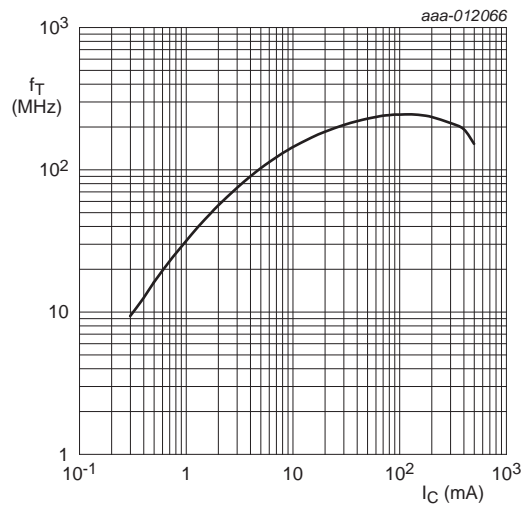
$T_{amb} = 25$  °C

**Fig 43. PDTD143XU: Collector current as a function of collector-emitter voltage; typical values**



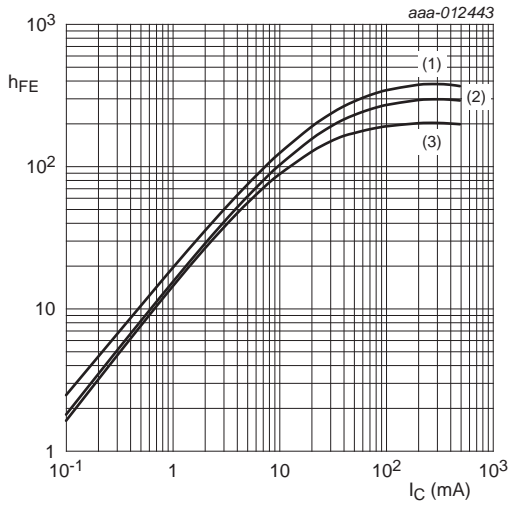
$f = 1$  MHz;  $T_{amb} = 25$  °C

**Fig 44. PDTD143XU: Collector capacitance as a function of collector-base voltage; typical values**



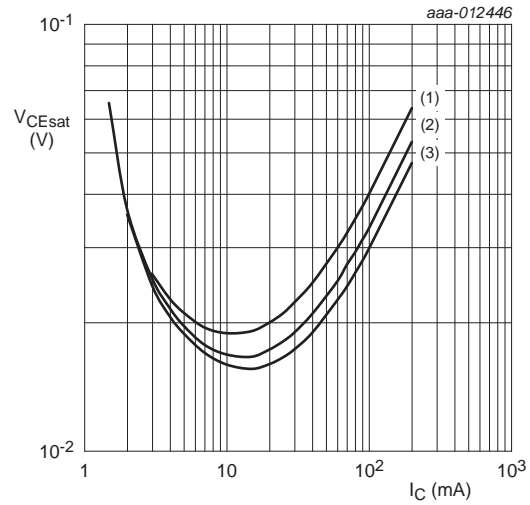
$V_{CE} = 5$  V;  $T_{amb} = 25$  °C

**Fig 45. PDTD143XU: Transition frequency as a function of collector current; typical values of built-in transistor**



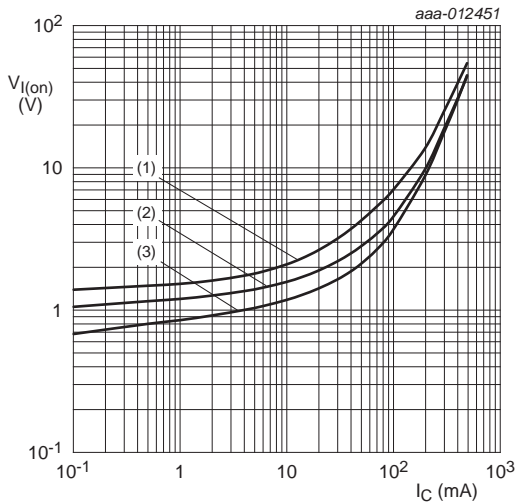
$V_{CE} = 5 \text{ V}$   
 (1)  $T_{amb} = 100 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = -40 \text{ }^\circ\text{C}$

**Fig 46. PDTD114EU: DC current gain as a function of collector current; typical values**



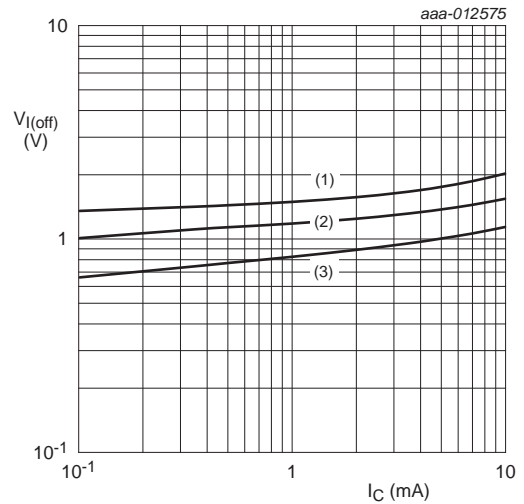
$I_C/I_B = 20$   
 (1)  $T_{amb} = 100 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = -40 \text{ }^\circ\text{C}$

**Fig 47. PDTD114EU: Collector-emitter saturation voltage as a function of collector current; typical values**



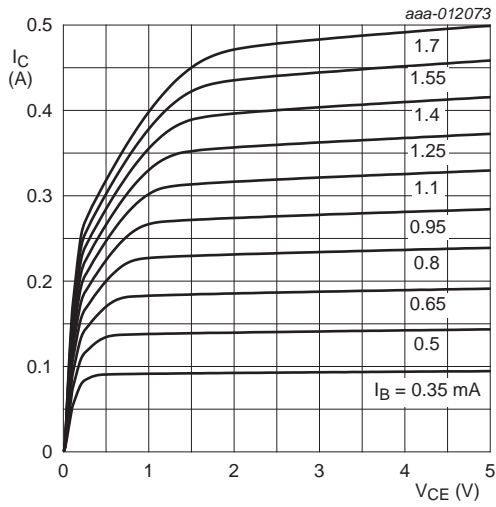
$V_{CE} = 0.3 \text{ V}$   
 (1)  $T_{amb} = -40 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = 100 \text{ }^\circ\text{C}$

**Fig 48. PDTD114EU: On-state input voltage as a function of collector current; typical values**



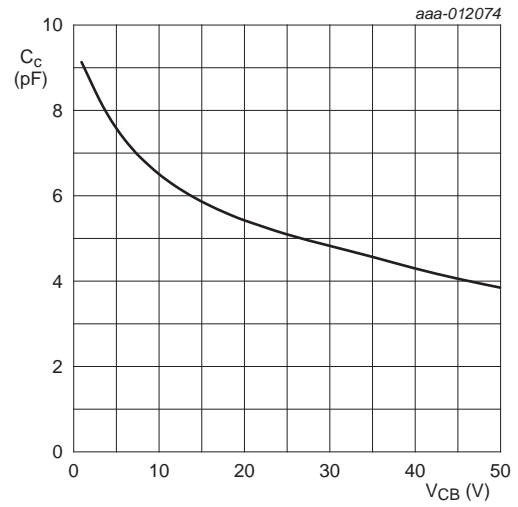
$V_{CE} = 5 \text{ V}$   
 (1)  $T_{amb} = -40 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = 100 \text{ }^\circ\text{C}$

**Fig 49. PDTD114EU: Off-state input voltage as a function of collector current; typical values**



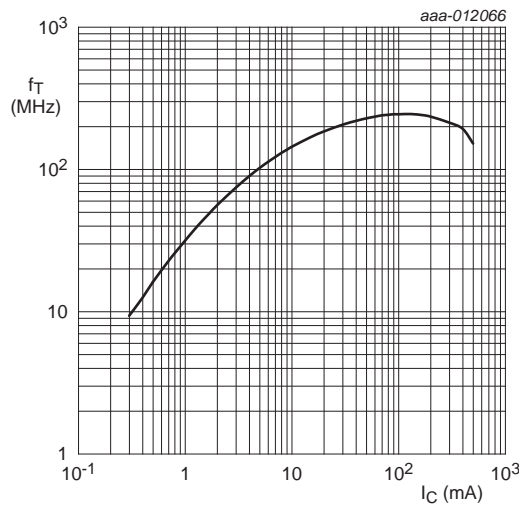
$T_{amb} = 25^\circ\text{C}$

**Fig 50. PDTD114EU: Collector current as a function of collector-emitter voltage; typical values**



$f = 1$  MHz;  $T_{amb} = 25^\circ\text{C}$

**Fig 51. PDTD114EU: Collector capacitance as a function of collector-base voltage; typical values**



$V_{CE} = 5$  V;  $T_{amb} = 25^\circ\text{C}$

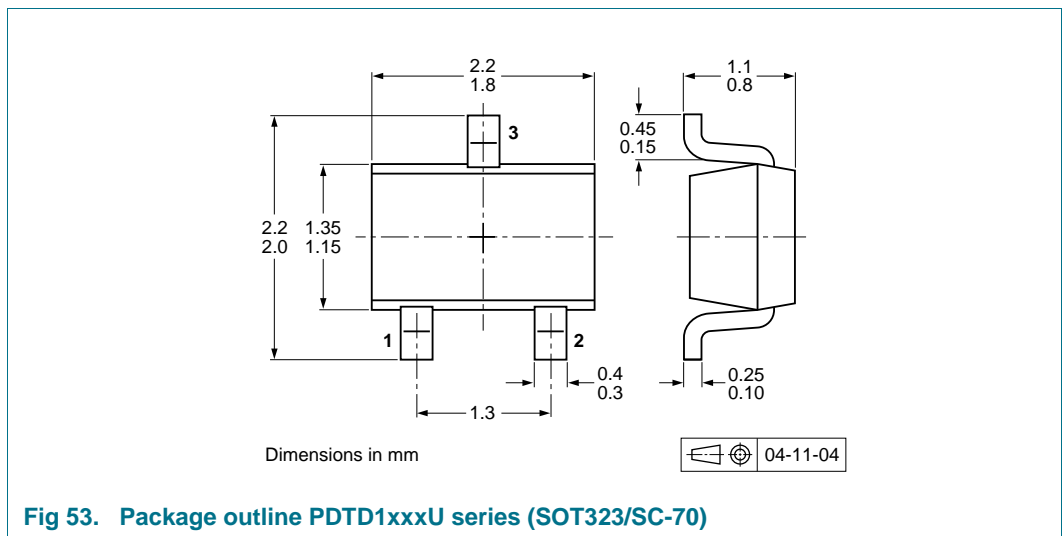
**Fig 52. PDTD114EU: Transition frequency as a function of collector current; typical values of built-in transistor**

## 8. Test information

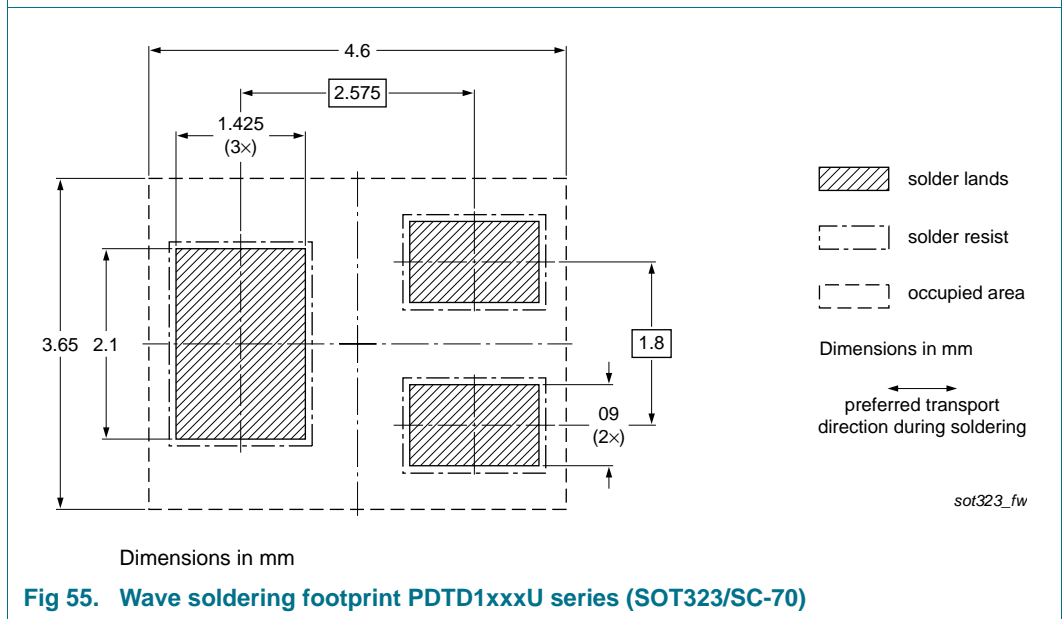
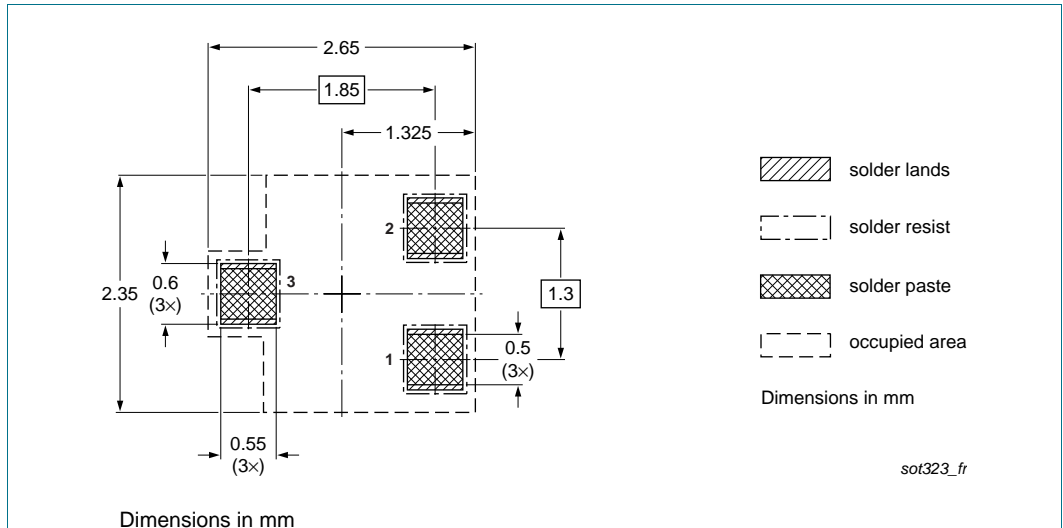
### 8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

## 9. Package outline



**10. Soldering**



## 11. Revision history

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**Table 9.** Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PDTD1XXXU_SER v.1	20140513	Product data sheet	-	-



## 12. Legal information

### 12.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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Date of release: 13 May 2014

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